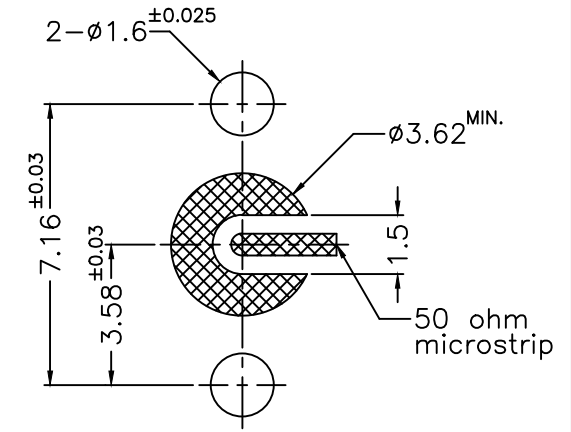
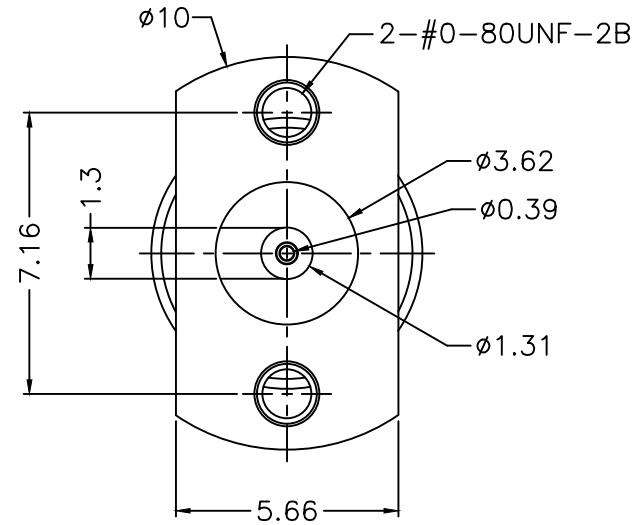
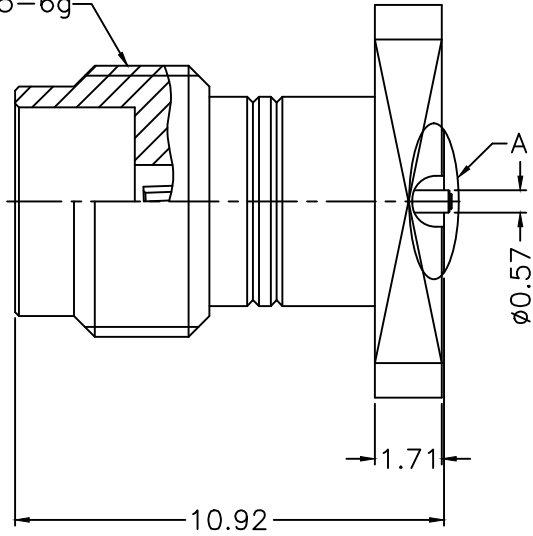


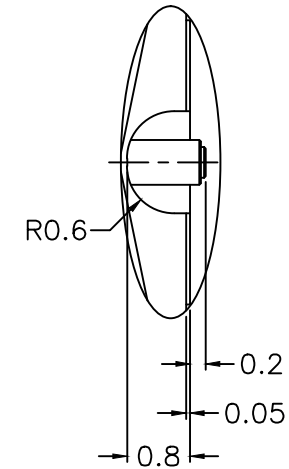
REVISIONS

ISS	ZONE	DESCRIPTION\PER REQUEST\DATE
A1	C-4	NO.6 SEPARATE FROM NO.5\N/A\06-15-'23

M7XP0.75-6g



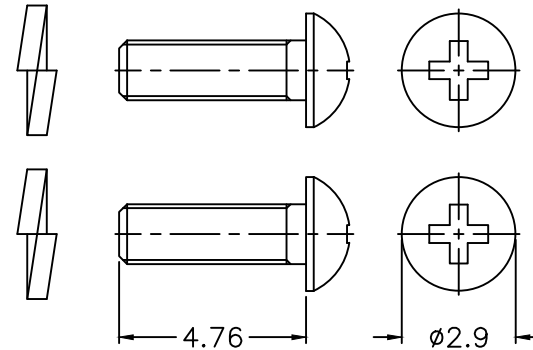
PCB MOUNTING PATTERN
(印刷电路板架设模型)



A DETAIL (10/1)
(A 詳圖)

NOTES: FINISH (PLATING THICKNESS IN MICRO-INCHES)

1. STAINLESS STEEL
2. PASSIVATED
3. BERYLLIUM COPPER
4. GOLD PL. 10 MIN. THICK OVER ELECTROLESS NICKEL PL. 100 MIN. THICK
5. PTFE
6. BRASS
7. NICKEL PL. 100 MIN. THICK OVER COPPER PL. 50 MIN. THICK



RoHS, REACH Compliance

NO.	DESCRIPTION	MATERIAL	FINISH	Q'TY	DRAWING NO.
6	WASHER		NOTE 1	NOTE 2	
5	BOLT		NOTE 1	NOTE 2	
4	BODY		NOTE 1	NOTE 2	
3	CONTACT PIN		NOTE 3	NOTE 4	
2	INSULATOR		NOTE 5	NATURAL	
1	RING		NOTE 6	NOTE 7	

DIMENSIONS ARE IN MILLIMETERS			
UNLESS OTHERWISE SPECIFIED TOLERANCES			
0.5-6	=	±0.2	
6-30	=	±0.4	
30-120	=	±0.6	
120-315	=	±1	
315-1000	=	±1.6	
1000-2000	=	±2.4	

PART NO.	
APPROVED	DATE 06-15-'23
CHECKED	DATE 06-15-'23
DRAWN	DATE 06-15-'23

G.L.I.	
TITLE	1.85mm SOLDERLESS PCB COMPRESSION MOUNT JACK
DRAWING NO.	185-6551F2-50
FILE NO.	R:\D\DWG\185\6551F2\50-A1